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TITLE : COPPER ALLOY FIBER AND COPPER ALLOY FIBER BUNDLE TO BE ADDED TO CONDUCTIVE PLASTIC

ABSTRACT : PURPOSE: To improve electromagnetic wave shielding characteristics of an injection-molded product and prevent deterioration of the characteristics at the time of long-term use by simultaneously adding to Cu Zn and one or two or more of Al, Mg, Sn and Cr.

CONSTITUTION: Copper alloy fiber comprises 5 to 45wt.% of Zn and a total of 0.1 to 2.0wt.% of one or two or more of Al, Mg, Sn and Cr with the remainder being Cu and inevitable impurities. The diameter of the copper alloy fiber is appropriately 0.08 to 0.03mmφ while the amount to be blended into thermoplastic resin is appropriately 20 to 40wt.%. Thus the metallic fiber is inexpensive, and a molded product obtained by injection-molding conductive plastic compound wherein this metallic fiber is blended into thermoplastic resin has excellent electromagnetic wave shielding effect whose characteristics will not deteriorate even after a long-term use.

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